L Number	Hits	Search Text	DB	Time stamp
1	909531	(upper or top$5 or high$3) with layer$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:14
2	143656	((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:15
3	15969	((upper or top$5 or high$3) with layer$5) with (config$10 or custom$10)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:48
4	631	(((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$1)) same (((upper or top$5 or high$3) with layer$5) with (config$10 or custom$10))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:16
5	345	(((upper or top$5 or high$3) with layer$5) with (config$10 or custom$10)) with (short$5 or fus$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:18
6	21	(((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$1)) same ((((upper or top$5 or high$3) with layer$5) with (config$10 or custom$10)) with (short$5 or fus$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:26
7	30745	passiv$8 adj5 layer$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:28
8	5079	(((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$1)) same (passiv$8 adj5 layer$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:28
9	214	((((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$1)) same (passiv$8 adj5 layer$3)) same (config$10 or custom$10)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:29
10	72	(((((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$1)) same (passiv$8 adj5 layer$3)) same (config$10 or custom$10)) same ((upper or top$5 or high$3) with layer$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:29

11	1154	((upper or top$5 or high$3) with layer$5) with custom$10	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:49
12	83	(((upper or top$5 or high$3) with layer$5) with custom$10) same (((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:49
-	2	6718424.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 10:45
-	2	6151651.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 13:33
-	91925	(ic$1 or integrated adj2 circuit$2) with layer$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 13:34
-	143656	(ic$1 or integrated adj2 circuit$2 or chip$5) with layer$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 13:37
-	19915	short$3 with ((upper or top$5 or high$3) with layer$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 13:37
-	768	((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$1) same (short$3 with ((upper or top$5 or high$3) with layer$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:15
-	86	(short$3 with ((upper or top$5 or high$3) with layer$1)) with delay$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 13:38
-	32	((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$1) same ((short$3 with ((upper or top$5 or high$3) with layer$1)) with delay$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 13:37

-	18	((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$1) same ((short$3 with ((upper or top$5 or high$3) with layer$1)) with delay$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 13:37
-	145730	(ic$1 or integrated adj2 circuit$2 or chip$5) with layer$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 13:37
-	20128	short$3 with ((upper or top$5 or high$3) with layer$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 13:38
-	87	(short$3 with ((upper or top$5 or high$3) with layer$5)) with delay$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 13:38
-	18	((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$5) same ((short$3 with ((upper or top$5 or high$3) with layer$5)) with delay$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/29 13:40
-	779	((ic$1 or integrated adj2 circuit$2 or chip$5) with layer$5) same (short$3 with ((upper or top$5 or high$3) with layer$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/30 09:13